EXPRESS MAIL NO. EL990358685US
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants	: Sion C. Quinlan and Tim J. Bales	Attorney Docket No.:	30022/US/3
Filed	: Concurrently herewith	Customer No.	: 27,076
Title	: SEMICONDUCTOR PACKAGE ASSEMBLY AND METHOD FOR ELECTRICALLY ISOLATING MODULES		

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97 through 1.98, applicant wishes to make known to the Patent and Trademark Office the references set forth on the attached form PTO-1449 (copies of the cited references, as required under 37 C.F.R. § 1.98, are enclosed). Although the aforesaid references are made known to the Patent and Trademark Office in compliance with applicant's duty to disclose all information he is aware of which is believed relevant to the examination of the above-identified application, applicant believes that his invention is patentable.

Please acknowledge receipt of this Information Disclosure Statement and kindly make the cited references of record in the above-identified application.

Respectfully submitted,
DORSEY & WHITNEY LLP

Steven H. Arterberry
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SHA:tlm
Enclosures:
Postcard
Form PTO-1449
Cited References (36)

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FORM PTO-1449 (REV.7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 30022/US/3	APPLICATION NO. Not Yet Assigned
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INFORMATION DISCLOSURE STATEMENT *(Use several sheets if necessary)*		FILING DATE Concurrently herewith	GROUP ART UNIT not yet assigned

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	5,975,958	11-02-99	Weidler	439	620	
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	AJ	Al-sarawi, Said F., "Wire Bonded Stacked Chips," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node35," January 25, 2002, pp. 1-2
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	BH	Willis, P. J., "Communication Protocols," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/chapter2_6.html," August 17, 2001, p. 1
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	BO	Embedded Systems Programming, "Fundamentals of Firewire," obtained at website "http://www.embedded.com/1999/9906/9906feat2.htm," August 28, 2001, pp. 1-14
	BP	Microprocessor and Microcomputer Standards Committee of the IEEE Computer Society, "P1394a Draft Standard for a High Performance Serial Bus (Supplement)," The Institute of Electrical and Electronics Engineers, Inc., June 30, 1999, pp.1-27
	BQ	Lucent Technologies, Inc., "IEEE 1394 Isolation," Application Note, November 1998, obtained at website "http://www.agere.com/1394/docs/AP98074-01.pdf," pp. 1-16

EXAMINER	DATE CONSIDERED

* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).